

MCM2128

16K BIT STATIC RAM

The MCM2128 is a 16,384-bit Static Random Access Memory organized as 2048 words by 8 bits, fabricated using Motorola's Highperformance silicon-gate MOS (HMOS) technology. It uses an innovative design approach which combines the ease-of-use features of fully static operation (no external clocks or timing strobes required) with the reduced standby power dissipation associated with clocked memories. To the user this means low standby power dissipation without the need for address setup and hold times, nor reduced data rates due to cycle times that are longer than access times.

Chip Enable $(\overline{\bf E})$ controls the power-down feature. It is not a clock but rather a chip control that affects power consumption. In less than a cycle time after chip enable $(\overline{\bf E})$ goes high, the part automatically reduces its power requirements and remains in this low-power standby mode as long as the chip enable $(\overline{\bf E})$ remains high. This feature provides significant system-level power savings.

The MCM2128 is in a 24-pin dual-in-line 300 mil wide package with the industry standard JEDEC approved pinout. A 24 pin dual-in-line 600 mil wide package is also available.

Single +5 Volt Operation (±10%)

• Fully Static: No Clock or Timing Strobe Required

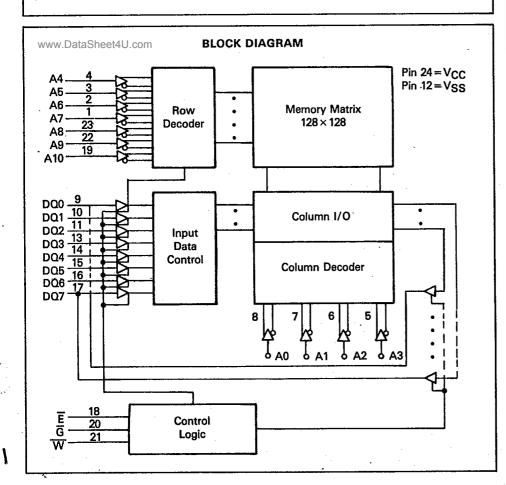
• Fast Access Time: MCM2128-10 - 100 ns (Maximum)

MCM2128-12 - 120 ns (Maximum) MCM2128-15 - 150 ns (Maximum)

Power Dissipation: 120 mA Maximum (Active)

20 mA Maximum (Standby)

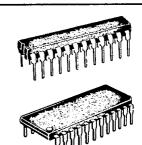
• Three-State Output



MOS

(N-CHANNEL, SILICON-GATE)

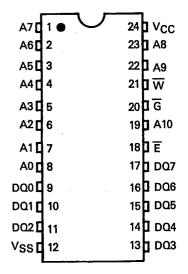
2,048×8 BIT STATIC RANDOM ACCESS MEMORY



N PACKAGE 300 MIL PLASTIC CASE 724

P PACKAGE 600 MIL PLASTIC CASE 709

PIN ASSIGNMENTS



PIN NAMES				
A0-A10	Address input			
DQ0-DQ7	Address InputData Input/OutputWrite Enable			
₩	Write Enable			
<u>G</u>	Output Enable			
Ē	Chip Enable			
Vcc	+ 5 V Power Supply			
V _{SS}	Ground			



ABSOLUTE MAXIMUM RATINGS (See Note)

Rating	Value	Unit
Temperature Under Bias	-10 to +80	°C
Voltage on Any Pin With Respect to VSS	-0.5 to +7.0	٧
DC Output Current	20	mA
Power Dissipation	0.9	Watt
Operating Temperature Range	0 to +70	°C
Storage Temperature Range	-65 to +150	°C

This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields; however, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages to this high-impedance circuit.

NOTE: Permanent device damage may occur if ABSOLUTE MAXIMUM RATINGS are exceeded. Functional operation should be restricted to RECOMMENDED OPERATING CONDITIONS. Exposure to higher than recommended voltages for extended periods of time could affect device reliability.

DC OPERATING CONDITIONS AND CHARACTERISTICS

(Full operating voltage and temperature range unless otherwise noted.)

RECOMMENDED OPERATING CONDITIONS

ALGOMINICITED OF LINA	Parameter	Symbol	Min	Тур	Max	Unit
Supply Voltage		Vcc	4.5	5.0	5.5	V
Cuppi, Tollage	•	V _{SS}	0	0	0	V
Input Voltage		VIH	2.0	3.0	6.0	V
mpar voicego		VIL	-0.5*	0	0.8	V

^{*}The device will withstand undershoots to the -3 volt level with a maximum pulse width of 50 ns. This is periodically sampled rather than 100% tested.

DC CHARACTERISTICS

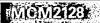
Parameter	Symbol	Min	Max	Unit
Input Leakage Current (V _{CC} =5.5 V, V _{in} =GND to V _{CC})	Ē	-1.0	+1.0	μΑ
Output Leakage Current (E=V _{IH} or G=V _{IH} , V _{I/O} =GND to V _{CC})	ILO	- 1.0	+1.0	μΑ
Operating Power Supply Current (E=V _{IL} , I _I /O=0 mA)	lcc1		120	mA
Standby Power Supply Current (E=V _{IH})	ISB	1	20	mA
Output Low Voltage (IOL = 4.0 mA) See Figure 1	V _{OL}	1	0.4	V
Output High Voltage (IOH = -2.0 mA) See Figure 1	Voн	2.4		V

CAPACITANCE (f=1.0 MHz, T_A=25°C, periodically sampled rather than 100% tested.)

Characteristic	Symbol	Тур	Max	Unit
Input Capacitance except E, DQ	Cin	3	5	pF
Input/Output Capacitance and E Input Capacitance	CI/O	5	7	рF
mput, output capetions				

MODE SELECTION

Mode	E	G	W	V _{CC} Current	DQ
Standby	Н	Х	Х	ISB	High Z
Read	L	L	Н	Icc	Q
Write Cycle	L	X	L	lcc	D



AC OPERATING CONDITIONS AND CHARACTERISTICS

(Full Operating Voltage and Temperature Range Unless Otherwise Noted)

Input Pulse Levels	Input and Output Timing Reference Levels
Input Rise and Fall Times	Output Load

READ CYCLE (See Notes 1 and 2)

Symbol		nbol	MCM2128-10		MCM2128-12		MCM2128-15		1	
Parameter	Standard	Alternate	Min	Max	Min	Max	Min	Max	Unit	
Address Valid to Address Valid (Read Cycle Time)	tAVAV	tRC	100		120	_	150		ns	
Address Valid to Output Valid (Address Access Time)	tAVQV	tAC	-	100	1	120		150	ns	
Chip Enable Low to Output Valid (Chip Enable Access Time)	tELQV	tACS	T	100		120		150	ns	
Output Enable Low to Output Valid (Output Enable Access Time)	tGLQV	tOE	-	35	-	50	_	55	ns	
Address Invalid to Output Invalid (Output Hold Time)	tAXQX	toH	10	-	10		10.		ns	
Chip Enable Low to Output Invalid (Chip Enable to Output Active)	†ELQX	tCLZ	5	-	5	_	5	_	ns	
Chip Enable High to Output High Z (Chip Disable to Output Disable) [2]	t _{EHOZ}	tCHZ		40	_	40	-	55	ns	
Output Enable Low to Output Invalid (Output Enable to Output Active)	tGLQX	tOLZ	5	-	5		5	_	ns	
Output Enable High to Output High Z (Output Disable to Output Disable) [2]	tGHOZ	tOHZ	_	35	_	35	_	50	ns	
Chip Enable Low to Power Up	tELICCH	tPU	0	_	0		0		ns	
Chip Enable High to Power Down	†EHICCL	tPD	-	50	_	60	-	60	ns	

NOTES:

1. Transition time specification applies for all input signals. In addition to meeting the transition rate specification, all input signals must transition between VIL and VIH (or between VIH and VIL) in a monotonic manner.

2. Transition is measured ±200 mV from the steady state output voltage with the output loading specified in Figure 1.

3. In read cycle 2, all addresses are valid prior to or coincident with chip enable (E) transition low.

WRITE CYCLE (See Notes 1, 3, 4 and 5)

	Symbol		мсма	128-10	мсма	2128-12	мсма	2128-15	
Parameter	Standard	Alternate	Min	Max	Min	Max	Min	Max	Unit
Address Valid to Address Valid (Write Cycle Time)	tAVAV	tWC	100		120		150		ns
Chip Enable Low to Write High (Chip Enable to End of Write)	tELWH	tEW	80		100		120		ns
Address Valid to Write Low (Address Setup to End of Write)	tAVWL	tAS	10		10	_	10		ns
Write Low to Write High (Write Pulse Width)	tWLWH	tWP	70		85		100		ns
Write High to Address Don't Care (Address Hold After End of Write)	twhax	tWR	0	_	0	_	0		ns
Data Valid to Write High (Data Setup to End of Write)	tDVWH	tDS	40	_	50	-	60	<u> </u>	ns
Write High to Data Don't Care (Data Hold After End of Write)	tWHDX	t _{DH}	5	-	5	_	5	_	ns
Write High to Output Don't Care (Output Active After End of Write)	twhox	tWLZ	5	_	5		5	_	ns
Write Low to Output High Z (Write Enable to Output Disable)	tWLQZ	tWHZ	_	30	_	35		50	ns

NOTES:

1. Write enable (W) must be high during all address transitions.

2. twhax is measured from the earlier of chip enable (E) or write enable (W) going high to the end of write cycle.

3. A write occurs during the overlap of low \overline{E} and low \overline{W} .

4. telwh is specified as the time from the chip selection to end of write in write cycle and twlwh is specified as the overlap time of low E and low W.

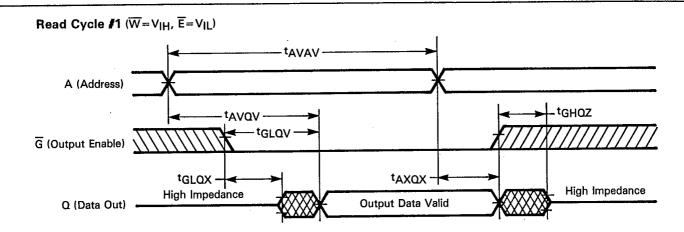
5. Output enable (G) can be low or high in write cycle, if G is high the output buffers will remain in the high impedance state.

6. If chip enable (E) and output enable (G) are low during this period, DQ pins are in the output state. Then the data input signals of opposite phase to the outputs must not be applied to them.

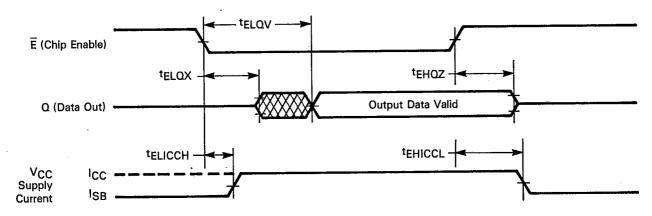
7. If the chip enable (E) low transition occurs simultaneously with or later than the write enable (W) low transition, the output buffers will remain in the high impedance state.

8. If the chip enable (E) high transition occurs simultaneously with the write enable (W) high transition, the output buffers will remain in the high impedance state.

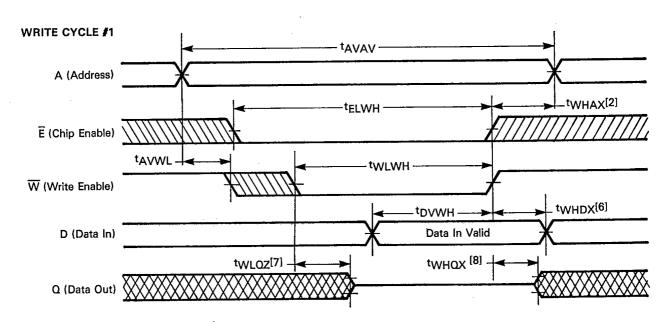


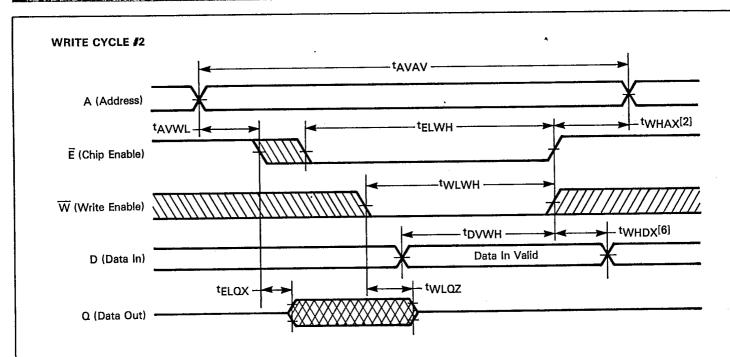


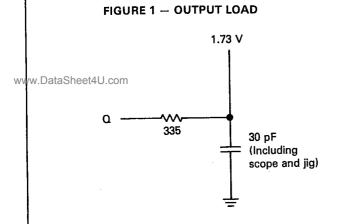
Read Cycle #2 $(\overline{W} = V_{IH}, \overline{G} = V_{IL})$ (See Note 3)

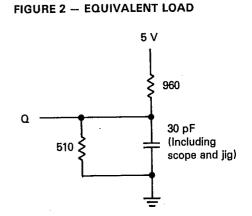


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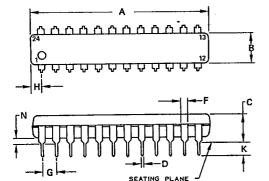








PACKAGE DIMENSIONS



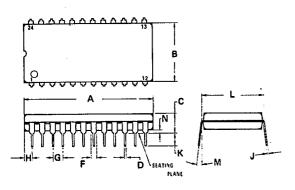
N PACKAGE PLASTIC CASE 724-02



NOTE:

1. LEADS, TRUE POSITIONED WITHIN 0.25 mm (0.010) DIA AT SEATING PLANE AT MAXIMUM MATERIAL CONDITION (DIM D).

	MILLIM	ETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
A	31.24	32.13	1.230	1.265	
В	6.35	6.86	0.250	0.270	
C	4.06	4.57	0.160	0.180	
D	0.38	0.51	0.015	0.020	
F	1.02	1.52	0.040	0.060	
G	2.54	BSC	0.100 BSC		
Н	1.60	2.11	0.063	0.083	
J	0.18	0.30	0.007	0.012	
К	2.92	3.43	0.115	0.135	
L	7.37	7.87	0.290	0.310	
M	_	10°		100	
N	0.51	1.02	0.020	0.040	



P PACKAGE PLASTIC CASE 709-02

NOTES:

- 1. POSITIONAL TOLERANCE OF LEADS (D), SHALL BE WITHIN 0.25 mm (0.010) AT MAXIMUM MATERIAL CONDITION, IN RELATION TO SEATING PLANE AND EACH OTHER.
- 2. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
- 3. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

	MILLIN	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	31.37	32,13	1.235	1.265
В	13.72	14.22	0.540	0.560
C	3.94	5.08	0.155	0.200
D	0.36	0.66	0.014	0.022
F	1.02	1.52	0.040	0,060
G	2.54	BSC	0.100	BSC
H	1,65	2.03	0.065	0.080
Ţ	0.20	0.38	0.008	0.015
K	2.92	3.43	0.115	0.135
L	15.24	BSC	0.600	
M	00	150	00	15 ⁰
N	0.51	1.02	0.020	0.040

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